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## BGA TWTK-BGAP-11 plaiting kit

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Product ID: 1871

Price: **9.80 EUR**

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Product weight: **0.01 kg**

### Description:

BGA TWTK-BGAP-11 plaiting kit it's a 11 set matrix for that's needed tool when you have to exchange BGA parts of your phone. It's supports Samsung E708, E808, D508 and D500 chipsets. Click to link for bigger photo - [LINK](#)

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